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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	20000
Total RAM Bits	405504
Number of I/O	188
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp20c-5fn256c

LatticeXP Family Data Sheet Introduction

July 2007 | Data Sheet DS1001

Features

- **Non-volatile, Infinitely Reconfigurable**
  - Instant-on – powers up in microseconds
  - No external configuration memory
  - Excellent design security, no bit stream to intercept
  - Reconfigure SRAM based logic in milliseconds
  - SRAM and non-volatile memory programmable through system configuration and JTAG ports
- **Sleep Mode**
  - Allows up to 1000x static current reduction
- **TransFR™ Reconfiguration (TFR)**
  - In-field logic update while system operates
- **Extensive Density and Package Options**
  - 3.1K to 19.7K LUT4s
  - 62 to 340 I/Os
  - Density migration supported
- **Embedded and Distributed Memory**
  - 54 Kbits to 396 Kbits sysMEM™ Embedded Block RAM
  - Up to 79 Kbits distributed RAM
  - Flexible memory resources:
    - Distributed and block memory
- **Flexible I/O Buffer**
  - Programmable sysIO™ buffer supports wide range of interfaces:
    - LVCMOS 3.3/2.5/1.8/1.5/1.2
    - LVTTL
    - SSTL 18 Class I
    - SSTL 3/2 Class I, II
    - HSTL15 Class I, III
    - HSTL 18 Class I, II, III
    - PCI
    - LVDS, Bus-LVDS, LVPECL, RSDS
- **Dedicated DDR Memory Support**
  - Implements interface up to DDR333 (166MHz)
- **sysCLOCK™ PLLs**
  - Up to 4 analog PLLs per device
  - Clock multiply, divide and phase shifting
- **System Level Support**
  - IEEE Standard 1149.1 Boundary Scan, plus ispTRACY™ internal logic analyzer capability
  - Onboard oscillator for configuration
  - Devices operate with 3.3V, 2.5V, 1.8V or 1.2V power supply

Table 1-1. LatticeXP Family Selection Guide

Device	LFXP3	LFXP6	LFXP10	LFXP15	LFXP20
PFU/PFF Rows	16	24	32	40	44
PFU/PFF Columns	24	30	38	48	56
PFU/PFF (Total)	384	720	1216	1932	2464
LUTs (K)	3	6	10	15	20
Distributed RAM (KBits)	12	23	39	61	79
EBR SRAM (KBits)	54	72	216	324	396
EBR SRAM Blocks	6	8	24	36	44
V_{CC} Voltage	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V
PLLs	2	2	4	4	4
Max. I/O	136	188	244	300	340
Packages and I/O Combinations:					
100-pin TQFP (14 x 14 mm)	62				
144-pin TQFP (20 x 20 mm)	100	100			
208-pin PQFP (28 x 28 mm)	136	142			
256-ball fpBGA (17 x 17 mm)		188	188	188	188
388-ball fpBGA (23 x 23 mm)			244	268	268
484-ball fpBGA (23 x 23 mm)				300	340

Figure 2-10. PLL Diagram

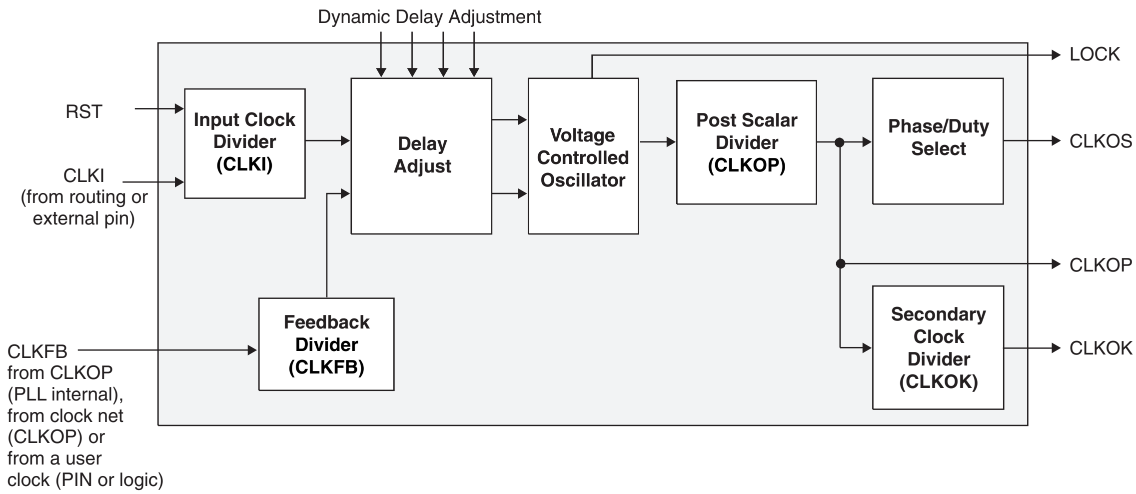


Figure 2-11 shows the available macros for the PLL. Table 2-11 provides signal description of the PLL Block.

Figure 2-11. PLL Primitive

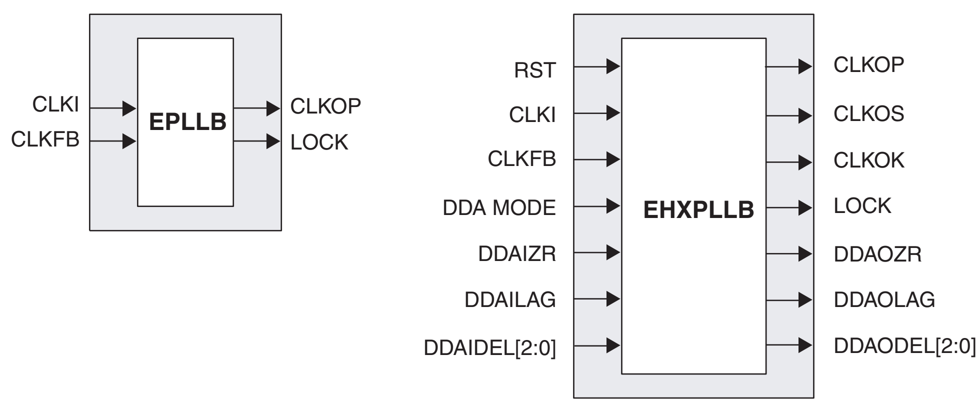


Table 2-5. PLL Signal Descriptions

Signal	I/O	Description
CLKI	I	Clock input from external pin or routing
CLKFB	I	PLL feedback input from CLKOP (PLL internal), from clock net (CLKOP) or from a user clock (PIN or logic)
RST	I	"1" to reset input clock divider
CLKOS	O	PLL output clock to clock tree (phase shifted/duty cycle changed)
CLKOP	O	PLL output clock to clock tree (No phase shift)
CLKOK	O	PLL output to clock tree through secondary clock divider
LOCK	O	"1" indicates PLL LOCK to CLKI
DDAMODE	I	Dynamic Delay Enable. "1" Pin control (dynamic), "0": Fuse Control (static)
DDAIZR	I	Dynamic Delay Zero. "1": delay = 0, "0": delay = on
DDAILAG	I	Dynamic Delay Lag/Lead. "1": Lag, "0": Lead
DDAIDEL[2:0]	I	Dynamic Delay Input
DDAOZR	O	Dynamic Delay Zero Output
DDAOLAG	O	Dynamic Delay Lag/Lead Output
DDAODEL[2:0]	O	Dynamic Delay Output

Figure 2-18. Group of Seven PIOs

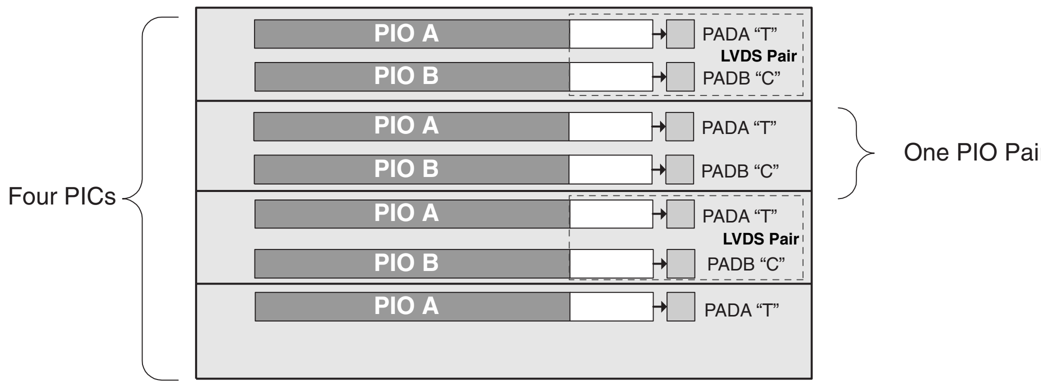
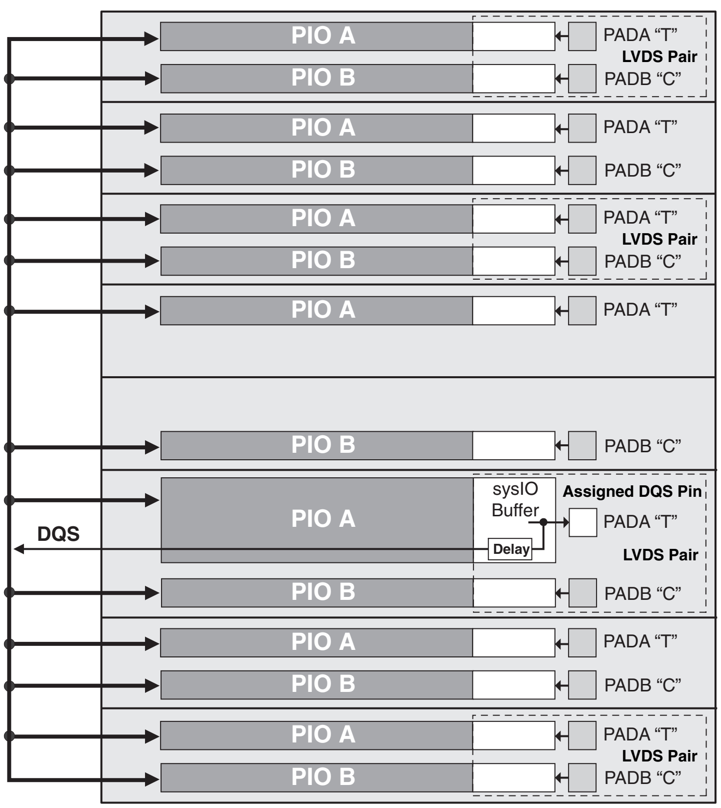


Figure 2-19. DQS Routing



PIO

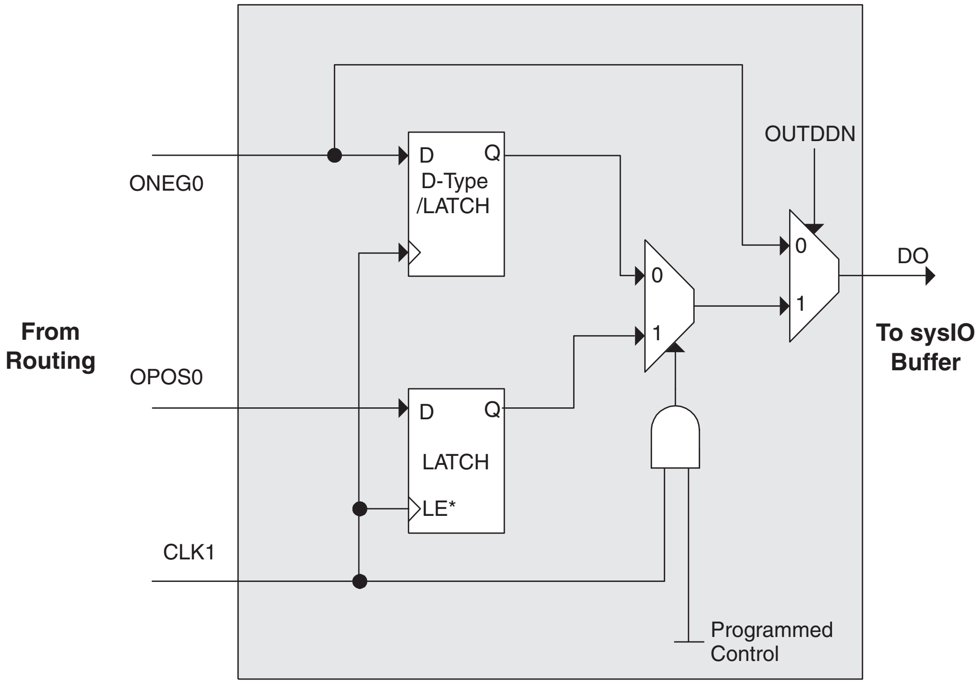
The PIO contains four blocks: an input register block, output register block, tristate register block and a control logic block. These blocks contain registers for both single data rate (SDR) and double data rate (DDR) operation along with the necessary clock and selection logic. Programmable delay lines used to shift incoming clock and data signals are also included in these blocks.

Input Register Block

The input register block contains delay elements and registers that can be used to condition signals before they are passed to the device core. Figure 2-20 shows the diagram of the input register block.

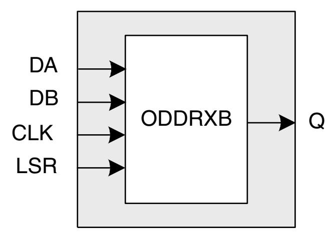
Input signals are fed from the sysIO buffer to the input register block (as signal DI). If desired the input signal can bypass the register and delay elements and be used directly as a combinatorial signal (INDD), a clock (INCK) and

Figure 2-23. Output Register Block



*Latch is transparent when input is low.

Figure 2-24. ODDRXB Primitive

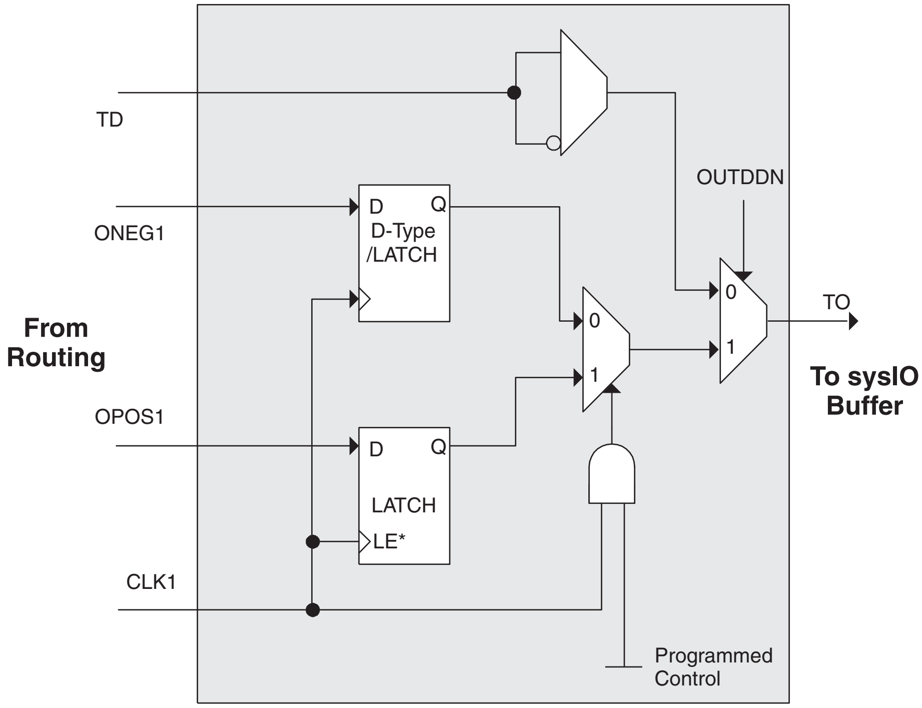


Tristate Register Block

The tristate register block provides the ability to register tri-state control signals from the core of the device before they are passed to the sysIO buffers. The block contains a register for SDR operation and an additional latch for DDR operation. Figure 2-25 shows the diagram of the Tristate Register Block.

In SDR mode, ONEG1 feeds one of the flip-flops that then feeds the output. The flip-flop can be configured a D-type or latch. In DDR mode, ONEG1 is fed into one register on the positive edge of the clock and OPOS1 is latched. A multiplexer running off the same clock selects the correct register for feeding to the output (D0).

Figure 2-25. Tristate Register Block



*Latch is transparent when input is low.

Control Logic Block

The control logic block allows the selection and modification of control signals for use in the PIO block. A clock is selected from one of the clock signals provided from the general purpose routing and a DQS signal provided from the programmable DQS pin. The clock can optionally be inverted.

The clock enable and local reset signals are selected from the routing and optionally inverted. The global tristate signal is passed through this block.

DDR Memory Support

Implementing high performance DDR memory interfaces requires dedicated DDR register structures in the input (for read operations) and in the output (for write operations). As indicated in the PIO Logic section, the LatticeXP devices provide this capability. In addition to these registers, the LatticeXP devices contain two elements to simplify the design of input structures for read operations: the DQS delay block and polarity control logic.

DLL Calibrated DQS Delay Block

Source Synchronous interfaces generally require the input clock to be adjusted in order to correctly capture data at the input register. For most interfaces a PLL is used for this adjustment, however in DDR memories the clock (referred to as DQS) is not free running so this approach cannot be used. The DQS Delay block provides the required clock alignment for DDR memory interfaces.

The DQS signal (selected PIOs only) feeds from the PAD through a DQS delay element to a dedicated DQS routing resource. The DQS signal also feeds the polarity control logic which controls the polarity of the clock to the sync registers in the input register blocks. Figures 2-26 and 2-27 show how the polarity control logic are routed to the PIOs.

The temperature, voltage and process variations of the DQS delay block are compensated by a set of calibration (6-bit bus) signals from two DLLs on opposite sides of the device. Each DLL compensates DQS Delays in its half of the device as shown in Figure 2-27. The DLL loop is compensated for temperature, voltage and process variations by the system clock and feedback loop.

Polarity Control Logic

In a typical DDR Memory interface design, the phase relation between the incoming delayed DQS strobe and the internal system Clock (during the READ cycle) is unknown.

The LatticeXP family contains dedicated circuits to transfer data between these domains. To prevent setup and hold violations at the domain transfer between DQS (delayed) and the system Clock a clock polarity selector is used. This changes the edge on which the data is registered in the synchronizing registers in the input register block. This requires evaluation at the start of the each READ cycle for the correct clock polarity.

Prior to the READ operation in DDR memories DQS is in tristate (pulled by termination). The DDR memory device drives DQS low at the start of the preamble state. A dedicated circuit detects this transition. This signal is used to control the polarity of the clock to the synchronizing registers.

sysIO Buffer

Each I/O is associated with a flexible buffer referred to as a sysIO buffer. These buffers are arranged around the periphery of the device in eight groups referred to as Banks. The sysIO buffers allow users to implement the wide variety of standards that are found in today's systems including LVCMOS, SSTL, HSTL, LVDS and LVPECL.

sysIO Buffer Banks

LatticeXP devices have eight sysIO buffer banks; each is capable of supporting multiple I/O standards. Each sysIO bank has its own I/O supply voltage (V_{CCIO}), and two voltage references V_{REF1} and V_{REF2} resources allowing each bank to be completely independent from each other. Figure 2-28 shows the eight banks and their associated supplies.

In the LatticeXP devices, single-ended output buffers and ratioed input buffers (LVTTL, LVCMOS, PCI and PCI-X) are powered using V_{CCIO}. LVTTL, LVCMOS33, LVCMOS25 and LVCMOS12 can also be set as a fixed threshold input independent of $V_{CCIO.}$ In addition to the bank V_{CCIO} supplies, the LatticeXP devices have a V_{CC} core logic power supply, and a V_{CCAUX} supply that power all differential and referenced buffers.

Each bank can support up to two separate VREF voltages, VREF1 and VREF2 that set the threshold for the referenced input buffers. In the LatticeXP devices, a dedicated pin in a bank can be configured to be a reference voltage supply pin. Each I/O is individually configurable based on the bank's supply and reference voltages.

Figure 2-29 provides a pictorial representation of the different programming ports and modes available in the LatticeXP devices.

On power-up, the FPGA SRAM is ready to be configured with the sysCONFIG port active. The IEEE 1149.1 serial mode can be activated any time after power-up by sending the appropriate command through the TAP port.

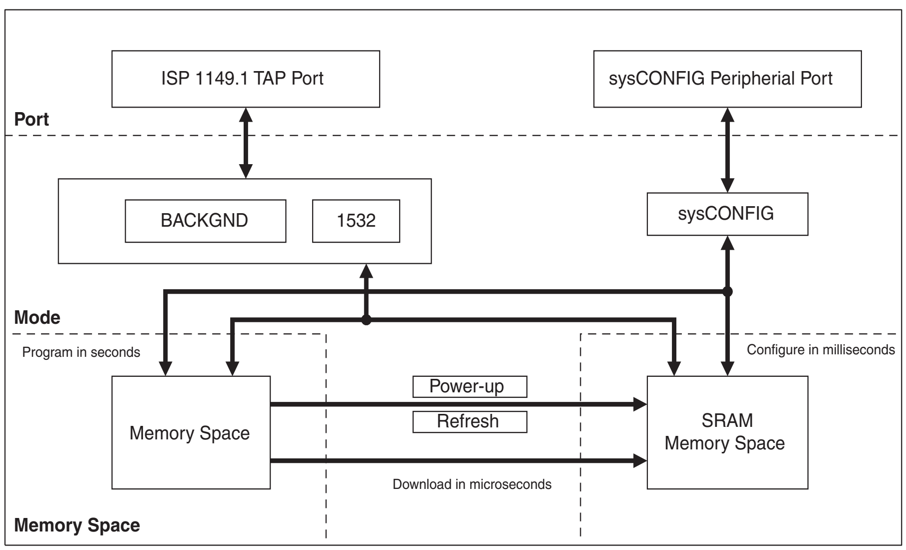
Leave Alone I/O
When using 1532 mode for non-volatile memory programming, users may specify I/Os as high, low, tristated or held at current value. This provides excellent flexibility for implementing systems where reprogramming occurs on-the-fly.

TransFR (Transparent Field Reconfiguration)
TransFR (TFR) is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a single ispVM command. See Lattice technical note #TN1087, *Minimizing System Interruption During Configuration Using TransFR Technology,* for details.

Security
The LatticeXP devices contain security bits that, when set, prevent the readback of the SRAM configuration and non-volatile memory spaces. Once set, the only way to clear security bits is to erase the memory space.

For more information on device configuration, please see details of additional technical documentation at the end of this data sheet.

Figure 2-29. ispXP Block Diagram



Internal Logic Analyzer Capability (ispTRACY)

All LatticeXP devices support an internal logic analyzer diagnostic feature. The diagnostic features provide capabilities similar to an external logic analyzer, such as programmable event and trigger condition and deep trace memory. This feature is enabled by Lattice's ispTRACY. The ispTRACY utility is added into the user design at compile time.

For more information on ispTRACY, please see information regarding additional technical documentation at the end of this data sheet.

Oscillator

Every LatticeXP device has an internal CMOS oscillator which is used to derive a master serial clock for configuration. The oscillator and the master serial clock run continuously in the configuration mode. The default value of the

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{IL}, I_{IH}[1, 2, 4]	Input or I/O Leakage	$0 \le V_{IN} \le (V_{CCIO} - 0.2V)$	—	—	10	µA
		$(V_{CCIO} - 0.2V) < V_{IN} \le 3.6V$	—	—	40	µA
I_{PU}	I/O Active Pull-up Current	$0 \le V_{IN} \le 0.7\ V_{CCIO}$	-30	—	-150	µA
I_{PD}	I/O Active Pull-down Current	V_{IL} (MAX) $\le V_{IN} \le V_{IH}$ (MAX)	30	—	150	µA
I_{BHLS}	Bus Hold Low sustaining current	$V_{IN} = V_{IL}$ (MAX)	30	—	—	µA
I_{BHHS}	Bus Hold High sustaining current	$V_{IN} = 0.7V_{CCIO}$	-30	—	—	µA
I_{BHLO}	Bus Hold Low Overdrive current	$0 \le V_{IN} \le V_{IH}$ (MAX)	—	—	150	µA
I_{BHHO}	Bus Hold High Overdrive current	$0 \le V_{IN} \le V_{IH}$ (MAX)	—	—	-150	µA
V_{BHT}	Bus Hold trip Points	$0 \le V_{IN} \le V_{IH}$ (MAX)	V_{IL} (MAX)	—	V_{IH} (MIN)	V
C1	I/O Capacitance[3]	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{IO} = 0 to V_{IH} (MAX)	—	8	—	pf
C2	Dedicated Input Capacitance[3]	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{IO} = 0 to V_{IH} (MAX)	—	8	—	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. Not applicable to SLEEPN/TOE pin.
3. T_A 25°C, f = 1.0MHz
4. When V_{IH} is higher than V_{CCIO}, a transient current typically of 30ns in duration or less with a peak current of 6mA can be expected on the high-to-low transition.

Supply Current (Sleep Mode)[1, 2, 3]

Symbol	Parameter	Device	Typ.[4]	Max	Units
I_{CC}	Core Power Supply	LFXP3C	12	65	µA
		LFXP6C	14	75	µA
		LFXP10C	16	85	µA
		LFXP15C	18	95	µA
		LFXP20C	20	105	µA
I_{CCP}	PLL Power Supply (per PLL)	All LFXP ‘C’ Devices	1	5	µA
I_{CCAUX}	Auxiliary Power Supply	LFXP3C	2	90	µA
		LFXP6C	2	100	µA
		LFXP10C	2	110	µA
		LFXP15C	3	120	µA
		LFXP20C	4	130	µA
I_{CCIO}	Bank Power Supply[5]	LFXP3C	2	20	µA
		LFXP6C	2	22	µA
		LFXP10C	2	24	µA
		LFXP15C	3	27	µA
		LFXP20C	4	30	µA
I_{CCJ}	VCCJ Power Supply	All LFXP ‘C’ Devices	1	5	µA

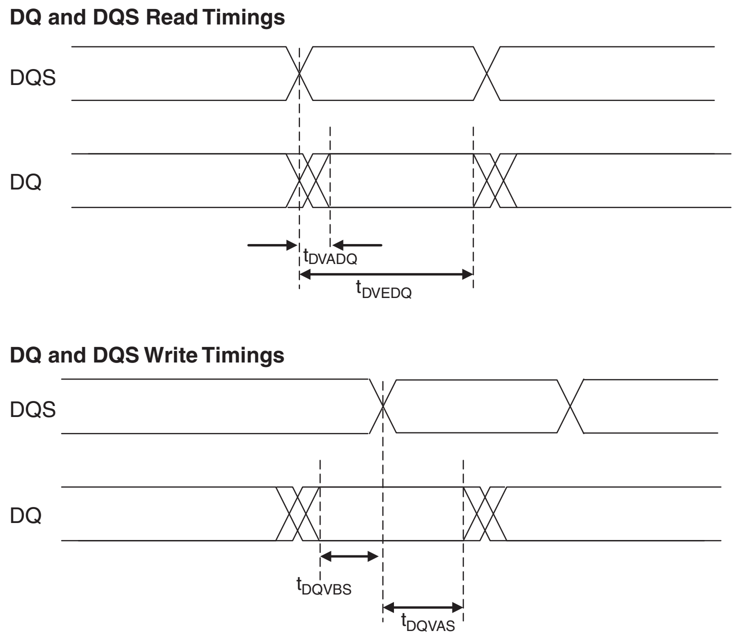
1. Assumes all inputs are configured as LVCMOS and held at the VCCIO or GND.
2. Frequency 0MHz.
3. User pattern: blank.
4. T_A=25°C, power supplies at nominal voltage.
5. Per bank.

sysIO Single-Ended DC Electrical Characteristics

Input/Output Standard	V_{IL}		V_{IH}		V_{OL} Max. (V)	V_{OH} Min. (V)	I_{OL} (mA)	I_{OH} (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVCMOS 3.3	-0.3	0.8	2.0	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVTTL	-0.3	0.8	2.0	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 2.5	-0.3	0.7	1.7	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.8	-0.3	0.35V_{CCIO}	0.65V_{CCIO}	3.6	0.4	V_{CCIO} - 0.4	16, 12, 8, 4	-16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.5	-0.3	0.35V_{CCIO}	0.65V_{CCIO}	3.6	0.4	V_{CCIO} - 0.4	8, 4	-8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.2 (“C” Version)	-0.3	0.42	0.78	3.6	0.4	V_{CCIO} - 0.4	6, 2	-6, -2
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.2 (“E” Version)	-0.3	0.35V_{CC}	0.65V_{CC}	3.6	0.4	V_{CCIO} - 0.4	6, 2	-6, -2
					0.2	V_{CCIO} - 0.2	0.1	-0.1
PCI	-0.3	0.3V_{CCIO}	0.5V_{CCIO}	3.6	0.1V_{CCIO}	0.9V_{CCIO}	1.5	-0.5
SSTL3 class I	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.7	V_{CCIO} - 1.1	8	-8
SSTL3 class II	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.5	V_{CCIO} - 0.9	16	-16
SSTL2 class I	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.54	V_{CCIO} - 0.62	7.6	-7.6
SSTL2 class II	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.35	V_{CCIO} - 0.43	15.2	-15.2
SSTL18 class I	-0.3	V_{REF} - 0.125	V_{REF} + 0.125	3.6	0.4	V_{CCIO} - 0.4	6.7	-6.7
HSTL15 class I	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	8	-8
HSTL15 class III	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	24	-8
HSTL18 class I	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	9.6	-9.6
HSTL18 class II	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	16	-16
HSTL18 class III	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	24	-8

1. The average DC current drawn by I/Os between GND connections, or between the last GND in an I/O bank and the end of an I/O bank, as shown in the logic signal connections table shall not exceed n * 8mA. Where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.

Figure 3-5. DDR Timings



Switching Test Conditions

Figure 3-13 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Figure 3-5.

Figure 3-13. Output Test Load, LVTTL and LVCMOS Standards

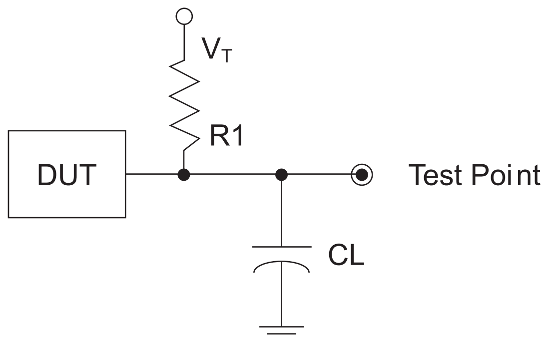


Table 3-5. Test Fixture Required Components, Non-Terminated Interfaces

Test Condition	R_1	C_L	Timing Ref.	V_T
LVTTL and other LVCMOS settings (L -> H, H -> L)	∞	0pF	LVCMOS 3.3 = 1.5V	—
			LVCMOS 2.5 = $V_{CCIO}/2$	—
			LVCMOS 1.8 = $V_{CCIO}/2$	—
			LVCMOS 1.5 = $V_{CCIO}/2$	—
			LVCMOS 1.2 = $V_{CCIO}/2$	—
LVCMOS 2.5 I/O (Z -> H)	188	0pF	$V_{CCIO}/2$	V_{OL}
LVCMOS 2.5 I/O (Z -> L)			$V_{CCIO}/2$	V_{OH}
LVCMOS 2.5 I/O (H -> Z)			V_{OH} - 0.15	V_{OL}
LVCMOS 2.5 I/O (L -> Z)			V_{OL} + 0.15	V_{OH}

Note: Output test conditions for all other interfaces are determined by the respective standards.

Pin Information Summary[1]

Pin Type		XP3 100 TQFP	XP3 144 TQFP	XP3 208 PQFP	XP6 144 TQFP	XP6 208 PQFP	XP6 256 fpBGA
Single Ended User I/O		62	100	136	100	142	188
Differential Pair User I/O[2]		19	35	56	35	58	80
Configuration	Dedicated	11	11	11	11	11	11
	Muxed	14	14	14	14	14	14
TAP		5	5	5	5	5	5
Dedicated (total without supplies)		6	6	6	6	6	6
V_{CC}		2	4	8	4	8	8
V_{CCAUX}		2	2	2	2	2	4
V_{CCPLL}		2	2	2	2	2	2
V_{CCIO}	Bank0	1	1	2	1	2	2
	Bank1	1	1	2	1	2	2
	Bank2	1	1	2	1	2	2
	Bank3	1	1	2	1	2	2
	Bank4	1	2	2	2	2	2
	Bank5	1	1	2	1	2	2
	Bank6	1	1	2	1	2	2
	Bank7	1	1	2	1	2	2
GND		10	13	24	13	24	24
GND_{PLL}		2	2	2	2	2	2
NC		0	0	6	0	0	0
Single Ended/Differential I/O per Bank[2]	Bank0	8/2	12/3	20/8	12/3	20/8	26/11
	Bank1	9/0	12/2	18/6	12/2	18/6	26/11
	Bank2	8/3	12/5	14/6	12/5	17/7	21/9
	Bank3	6/2	13/5	14/6	13/5	14/6	21/9
	Bank4	5/2	14/6	21/9	14/6	21/9	26/11
	Bank5	12/4	12/4	21/9	12/4	21/9	26/11
	Bank6	4/2	13/5	14/6	13/5	17/7	21/9
	Bank7	10/4	12/5	14/6	12/5	14/6	21/9
V_{CCJ}		1	1	1	1	1	1

1. During configuration the user-programmable I/Os are tri-stated with an internal pull-up resistor enabled. If any pin is not used (or not bonded to a package pin), it is also tri-stated with an internal pull-up resistor enabled after configuration.
2. The differential I/O per bank includes both dedicated LVDS and emulated LVDS pin pairs. Please see the Logic Signal Connections table for more information.

Pin Information Summary[1] (Cont.)

Pin Type		XP10 256 fpBGA	XP10 388 fpBGA	XP15 256 fpBGA	XP15 388 fpBGA	XP15 484 fpBGA	XP20 256 fpBGA	XP20 388 fpBGA	XP20 484 fpBGA
Single Ended User I/O		188	244	188	268	300	188	268	340
Differential Pair User I/O[2]		76	104	76	112	128	76	112	144
Configuration	Dedicated	11	11	11	11	11	11	11	11
	Muxed	14	14	14	14	14	14	14	14
TAP		5	5	5	5	5	5	5	5
Dedicated (total without supplies)		6	6	6	6	6	6	6	6
V_{CC}		8	14	8	14	28	8	14	28
V_{CCAUX}		4	4	4	4	12	4	4	12
V_{CCPLL}		2	2	2	2	2	2	2	2
V_{CCIO}	Bank0	2	5	2	5	4	2	5	4
	Bank1	2	5	2	5	4	2	5	4
	Bank2	2	4	2	4	4	2	4	4
	Bank3	2	4	2	4	4	2	4	4
	Bank4	2	5	2	5	4	2	5	4
	Bank5	2	5	2	5	4	2	5	4
	Bank6	2	4	2	4	4	2	4	4
	Bank7	2	4	2	4	4	2	4	4
GND		24	50	24	50	56	24	50	56
GND_{PLL}		2	2	2	2	2	2	2	2
NC		0	24	0	0	40	0	0	0
Single Ended/ Differential I/O per Bank[2]	Bank0	26/11	33/14	26/11	39/16	40/17	26/11	39/16	47/20
	Bank1	26/11	33/14	26/11	39/16	40/17	26/11	39/16	47/20
	Bank2	21/8	28/12	21/8	28/12	35/15	21/8	28/12	38/16
	Bank3	21/8	28/12	21/8	28/12	35/15	21/8	28/12	38/16
	Bank4	26/11	33/14	26/11	39/16	40/17	26/11	39/16	47/20
	Bank5	26/11	33/14	26/11	39/16	40/17	26/11	39/16	47/20
	Bank6	21/8	28/12	21/8	28/12	35/15	21/8	28/12	38/16
	Bank7	21/8	28/12	21/8	28/12	35/15	21/8	28/12	38/16
V_{CCJ}		1	1	1	1	1	1	1	1

1. During configuration the user-programmable I/Os are tri-stated with an internal pull-up resistor enabled. If any pin is not used (or not bonded to a package pin), it is also tri-stated with an internal pull-up resistor enabled after configuration.
2. The differential I/O per bank includes both dedicated LVDS and emulated LVDS pin pairs. Please see the Logic Signal Connections table for more information.

LFXP3 Logic Signal Connections: 100 TQFP (Cont.)

Pin Number	Pin Function	Bank	Differential	Dual Function
88	PT14B	1	-	D7
89	PT13B	0	C	BUSY
90	GNDIO0	0	-	-
91	PT13A	0	T	CS1N
92	PT12B	0	C	PCLKC0_0
93	PT12A	0	T	PCLKT0_0
94	VCCIO0	0	-	-
95	PT9A	0	-	DOUT
96	PT8A	0	-	WRITEN
97	PT6A	0	-	DI
98	PT5A	0	-	CSN
99	GND	-	-	-
100	CFG0	0	-	-

1. Applies to LFXP “C” only.
2. Applies to LFXP “E” only.
3. Supports dedicated LVDS outputs.

LFXP3 & LFXP6 Logic Signal Connections: 208 PQFP (Cont.)

Pin Number	LFXP3				LFXP6			
	Pin Function	Bank	Differential	Dual Function	Pin Function	Bank	Differential	Dual Function
139	PR7A	2	T[3]	DQS	PR7A	2	T[3]	DQS
140	VCCIO2	2	-	-	VCCIO2	2	-	-
141	PR6B	2	-	VREF1_2	PR6B	2	-	VREF1_2
142	PR5A	2	-	VREF2_2	PR5A	2	-	VREF2_2
143	GNDIO2	2	-	-	GNDIO2	2	-	-
144	PR4B	2	C[3]	-	PR4B	2	C[3]	-
145	PR4A	2	T[3]	-	PR4A	2	T[3]	-
146	PR3B	2	C	RUM0_PLLC_FB_A	PR3B	2	C	RUM0_PLLC_FB_A
147	PR3A	2	T	RUM0_PLLT_FB_A	PR3A	2	T	RUM0_PLLT_FB_A
148	PR2B	2	C[3]	-	PR2B	2	C[3]	-
149	VCCIO2	2	-	-	VCCIO2	2	-	-
150	PR2A	2	T[3]	-	PR2A	2	T[3]	-
151	VCC	-	-	-	VCC	-	-	-
152	VCCAUX	-	-	-	VCCAUX	-	-	-
153	TDO	-	-	-	TDO	-	-	-
154	VCCJ	-	-	-	VCCJ	-	-	-
155	TDI	-	-	-	TDI	-	-	-
156	TMS	-	-	-	TMS	-	-	-
157	TCK	-	-	-	TCK	-	-	-
158	VCC	-	-	-	VCC	-	-	-
159	PT25A	1	-	VREF1_1	PT28A	1	-	VREF1_1
160	PT24B	1	C	-	PT27B	1	C	-
161	PT24A	1	T	-	PT27A	1	T	-
162	PT23A	1	-	D0	PT26A	1	-	D0
163	GNDIO1	1	-	-	GNDIO1	1	-	-
164	PT22B	1	C	D1	PT25B	1	C	D1
165	PT22A	1	T	VREF2_1	PT25A	1	T	VREF2_1
166	PT21A	1	-	D2	PT24A	1	-	D2
167	VCCIO1	1	-	-	VCCIO1	1	-	-
168	PT20B	1	C	D3	PT23B	1	C	D3
169	PT20A	1	T	-	PT23A	1	T	-
170	PT19B	1	C	-	PT22B	1	C	-
171	PT19A	1	T	DQS	PT22A	1	T	DQS
172	GNDIO1	1	-	-	GNDIO1	1	-	-
173	PT18B	1	-	-	PT21B	1	-	-
174	PT17A	1	-	D4	PT20A	1	-	D4
175	PT16B	1	C	-	PT19B	1	C	-
176	PT16A	1	T	D5	PT19A	1	T	D5
177	VCCIO1	1	-	-	VCCIO1	1	-	-
178	PT15B	1	C	D6	PT18B	1	C	D6
179	PT15A	1	T	-	PT18A	1	T	-
180	PT14B	1	-	D7	PT17B	1	-	D7
181	GND	-	-	-	GND	-	-	-
182	VCC	-	-	-	VCC	-	-	-
183	PT13B	0	C	BUSY	PT16B	0	C	BUSY
184	GNDIO0	0	-	-	GNDIO0	0	-	-

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP15 Ball Function	LFXP15 Bank	LFXP15 Differential	LFXP15 Dual Function	LFXP20 Ball Function	LFXP20 Bank	LFXP20 Differential	LFXP20 Dual Function
L4	PL32A	6	-	-	PL36A	6	-	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
K4	PL33A	6	T	-	PL37A	6	T	-
K5	PL33B	6	C	-	PL37B	6	C	-
N1	PL35A	6	-	VREF2_6	PL39A	6	-	VREF2_6
N2	PL36B	6	-	-	PL40B	6	-	-
P1	PL37A	6	T[3]	DQS	PL41A	6	T[3]	DQS
P2	PL37B	6	C[3]	-	PL41B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
L5	PL38A	6	T	LLM0_PLLT_FB_A	PL42A	6	T	LLM0_PLLT_FB_A
M6	PL38B	6	C	LLM0_PLLC_FB_A	PL42B	6	C	LLM0_PLLC_FB_A
M3	PL39A	6	T[3]	-	PL43A	6	T[3]	-
N3	PL39B	6	C[3]	-	PL43B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
P4	SLEEPN[1]/TOE[2]	-	-	-	SLEEPN[1]/TOE[2]	-	-	-
P3	INITN	5	-	-	INITN	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
R4	PB11A	5	T	-	PB15A	5	T	-
N5	PB11B	5	C	-	PB15B	5	C	-
P5	PB12A	5	T	VREF1_5	PB16A	5	T	VREF1_5
-	GNDIO5	5	-	-	GNDIO5	5	-	-
R1	PB12B	5	C	-	PB16B	5	C	-
N6	PB13A	5	-	-	PB17A	5	-	-
M7	PB14B	5	-	-	PB18B	5	-	-
R2	PB15A	5	T	DQS	PB19A	5	T	DQS
T2	PB15B	5	C	-	PB19B	5	C	-
R3	PB16A	5	T	-	PB20A	5	T	-
T3	PB16B	5	C	-	PB20B	5	C	-
T4	PB17A	5	T	-	PB21A	5	T	-
R5	PB17B	5	C	VREF2_5	PB21B	5	C	VREF2_5
N7	PB18A	5	T	-	PB22A	5	T	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
M8	PB18B	5	C	-	PB22B	5	C	-
T5	PB19A	5	T	-	PB23A	5	T	-
P6	PB19B	5	C	-	PB23B	5	C	-
T6	PB20A	5	T	-	PB24A	5	T	-
R6	PB20B	5	C	-	PB24B	5	C	-
P7	PB21A	5	-	-	PB25A	5	-	-
N8	PB22B	5	-	-	PB26B	5	-	-
R7	PB23A	5	T	DQS	PB27A	5	T	DQS

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
T6	PL41A	6	T	-	PL45A	6	T	-
T5	PL41B	6	C	-	PL45B	6	C	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
U3	PL42A	6	T[3]	-	PL46A	6	T[3]	-
U4	PL42B	6	C[3]	-	PL46B	6	C[3]	-
V4	PL43A	6	-	-	PL47A	6	-	-
W4	SLEEPN[1]/ TOE[2]	-	-	-	SLEEPN[1]/ TOE[2]	-	-	-
W5	INITN	5	-	-	INITN	5	-	-
Y3	-	-	-	-	PB3B	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
U5	-	-	-	-	PB4A	5	T	-
V5	-	-	-	-	PB4B	5	C	-
Y4	-	-	-	-	PB5A	5	T	-
Y5	-	-	-	-	PB5B	5	C	-
V6	-	-	-	-	PB6A	5	T	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
U6	-	-	-	-	PB6B	5	C	-
W6	PB3A	5	T	-	PB7A	5	T	-
Y6	PB3B	5	C	-	PB7B	5	C	-
AA2	PB4A	5	T	-	PB8A	5	T	-
AA3	PB4B	5	C	-	PB8B	5	C	-
V7	PB5A	5	-	-	PB9A	5	-	-
U7	PB6B	5	-	-	PB10B	5	-	-
Y7	PB7A	5	T	DQS	PB11A	5	T	DQS
W7	PB7B	5	C	-	PB11B	5	C	-
AA4	PB8A	5	T	-	PB12A	5	T	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
AA5	PB8B	5	C	-	PB12B	5	C	-
AB3	PB9A	5	T	-	PB13A	5	T	-
AB4	PB9B	5	C	-	PB13B	5	C	-
AA6	PB10A	5	T	-	PB14A	5	T	-
AA7	PB10B	5	C	-	PB14B	5	C	-
U8	PB11A	5	T	-	PB15A	5	T	-
V8	PB11B	5	C	-	PB15B	5	C	-
Y8	PB12A	5	T	VREF1_5	PB16A	5	T	VREF1_5
-	GNDIO5	5	-	-	GNDIO5	5	-	-
W8	PB12B	5	C	-	PB16B	5	C	-
V9	PB13A	5	-	-	PB17A	5	-	-
U9	PB14B	5	-	-	PB18B	5	-	-
Y9	PB15A	5	T	DQS	PB19A	5	T	DQS
W9	PB15B	5	C	-	PB19B	5	C	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
J15	GND	-	-	-	GND	-	-	-
J8	GND	-	-	-	GND	-	-	-
J9	GND	-	-	-	GND	-	-	-
K10	GND	-	-	-	GND	-	-	-
K11	GND	-	-	-	GND	-	-	-
K12	GND	-	-	-	GND	-	-	-
K13	GND	-	-	-	GND	-	-	-
K14	GND	-	-	-	GND	-	-	-
K9	GND	-	-	-	GND	-	-	-
L10	GND	-	-	-	GND	-	-	-
L11	GND	-	-	-	GND	-	-	-
L12	GND	-	-	-	GND	-	-	-
L13	GND	-	-	-	GND	-	-	-
L14	GND	-	-	-	GND	-	-	-
L9	GND	-	-	-	GND	-	-	-
M10	GND	-	-	-	GND	-	-	-
M11	GND	-	-	-	GND	-	-	-
M12	GND	-	-	-	GND	-	-	-
M13	GND	-	-	-	GND	-	-	-
M14	GND	-	-	-	GND	-	-	-
M9	GND	-	-	-	GND	-	-	-
N10	GND	-	-	-	GND	-	-	-
N11	GND	-	-	-	GND	-	-	-
N12	GND	-	-	-	GND	-	-	-
N13	GND	-	-	-	GND	-	-	-
N14	GND	-	-	-	GND	-	-	-
N9	GND	-	-	-	GND	-	-	-
P10	GND	-	-	-	GND	-	-	-
P11	GND	-	-	-	GND	-	-	-
P12	GND	-	-	-	GND	-	-	-
P13	GND	-	-	-	GND	-	-	-
P14	GND	-	-	-	GND	-	-	-
P15	GND	-	-	-	GND	-	-	-
P8	GND	-	-	-	GND	-	-	-
P9	GND	-	-	-	GND	-	-	-
R14	GND	-	-	-	GND	-	-	-
R9	GND	-	-	-	GND	-	-	-
F10	VCC	-	-	-	VCC	-	-	-
F13	VCC	-	-	-	VCC	-	-	-
G10	VCC	-	-	-	VCC	-	-	-
G13	VCC	-	-	-	VCC	-	-	-
G14	VCC	-	-	-	VCC	-	-	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
G9	VCC	-	-	-	VCC	-	-	-
H15	VCC	-	-	-	VCC	-	-	-
H8	VCC	-	-	-	VCC	-	-	-
J16	VCC	-	-	-	VCC	-	-	-
J7	VCC	-	-	-	VCC	-	-	-
K16	VCC	-	-	-	VCC	-	-	-
K17	VCC	-	-	-	VCC	-	-	-
K6	VCC	-	-	-	VCC	-	-	-
K7	VCC	-	-	-	VCC	-	-	-
N16	VCC	-	-	-	VCC	-	-	-
N17	VCC	-	-	-	VCC	-	-	-
N6	VCC	-	-	-	VCC	-	-	-
N7	VCC	-	-	-	VCC	-	-	-
P16	VCC	-	-	-	VCC	-	-	-
P7	VCC	-	-	-	VCC	-	-	-
R15	VCC	-	-	-	VCC	-	-	-
R8	VCC	-	-	-	VCC	-	-	-
T10	VCC	-	-	-	VCC	-	-	-
T13	VCC	-	-	-	VCC	-	-	-
T14	VCC	-	-	-	VCC	-	-	-
T9	VCC	-	-	-	VCC	-	-	-
U10	VCC	-	-	-	VCC	-	-	-
U13	VCC	-	-	-	VCC	-	-	-
G15	VCCAUX	-	-	-	VCCAUX	-	-	-
G16	VCCAUX	-	-	-	VCCAUX	-	-	-
G7	VCCAUX	-	-	-	VCCAUX	-	-	-
G8	VCCAUX	-	-	-	VCCAUX	-	-	-
H16	VCCAUX	-	-	-	VCCAUX	-	-	-
H7	VCCAUX	-	-	-	VCCAUX	-	-	-
R16	VCCAUX	-	-	-	VCCAUX	-	-	-
R7	VCCAUX	-	-	-	VCCAUX	-	-	-
T15	VCCAUX	-	-	-	VCCAUX	-	-	-
T16	VCCAUX	-	-	-	VCCAUX	-	-	-
T7	VCCAUX	-	-	-	VCCAUX	-	-	-
T8	VCCAUX	-	-	-	VCCAUX	-	-	-
F11	VCCIO0	0	-	-	VCCIO0	0	-	-
G11	VCCIO0	0	-	-	VCCIO0	0	-	-
H10	VCCIO0	0	-	-	VCCIO0	0	-	-
H11	VCCIO0	0	-	-	VCCIO0	0	-	-
F12	VCCIO1	1	-	-	VCCIO1	1	-	-
G12	VCCIO1	1	-	-	VCCIO1	1	-	-
H12	VCCIO1	1	-	-	VCCIO1	1	-	-

Conventional Packaging

Commercial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3C-3Q208C	136	1.8/2.5/3.3V	-3	PQFP	208	COM	3.1K
LFXP3C-4Q208C	136	1.8/2.5/3.3V	-4	PQFP	208	COM	3.1K
LFXP3C-5Q208C	136	1.8/2.5/3.3V	-5	PQFP	208	COM	3.1K
LFXP3C-3T144C	100	1.8/2.5/3.3V	-3	TQFP	144	COM	3.1K
LFXP3C-4T144C	100	1.8/2.5/3.3V	-4	TQFP	144	COM	3.1K
LFXP3C-5T144C	100	1.8/2.5/3.3V	-5	TQFP	144	COM	3.1K
LFXP3C-3T100C	62	1.8/2.5/3.3V	-3	TQFP	100	COM	3.1K
LFXP3C-4T100C	62	1.8/2.5/3.3V	-4	TQFP	100	COM	3.1K
LFXP3C-5T100C	62	1.8/2.5/3.3V	-5	TQFP	100	COM	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6C-3F256C	188	1.8/2.5/3.3V	-3	fpBGA	256	COM	5.8K
LFXP6C-4F256C	188	1.8/2.5/3.3V	-4	fpBGA	256	COM	5.8K
LFXP6C-5F256C	188	1.8/2.5/3.3V	-5	fpBGA	256	COM	5.8K
LFXP6C-3Q208C	142	1.8/2.5/3.3V	-3	PQFP	208	COM	5.8K
LFXP6C-4Q208C	142	1.8/2.5/3.3V	-4	PQFP	208	COM	5.8K
LFXP6C-5Q208C	142	1.8/2.5/3.3V	-5	PQFP	208	COM	5.8K
LFXP6C-3T144C	100	1.8/2.5/3.3V	-3	TQFP	144	COM	5.8K
LFXP6C-4T144C	100	1.8/2.5/3.3V	-4	TQFP	144	COM	5.8K
LFXP6C-5T144C	100	1.8/2.5/3.3V	-5	TQFP	144	COM	5.8K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10C-3F388C	244	1.8/2.5/3.3V	-3	fpBGA	388	COM	9.7K
LFXP10C-4F388C	244	1.8/2.5/3.3V	-4	fpBGA	388	COM	9.7K
LFXP10C-5F388C	244	1.8/2.5/3.3V	-5	fpBGA	388	COM	9.7K
LFXP10C-3F256C	188	1.8/2.5/3.3V	-3	fpBGA	256	COM	9.7K
LFXP10C-4F256C	188	1.8/2.5/3.3V	-4	fpBGA	256	COM	9.7K
LFXP10C-5F256C	188	1.8/2.5/3.3V	-5	fpBGA	256	COM	9.7K